

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Xiao-Dong FEI	09/01/2020
Wei WANG	09/01/2020
San-Yueh HUANG	08/14/2020
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<b>State/Country:</b>	CHINA
<b>Name:</b>	FARADAY TECHNOLOGY CORP.
<b>Street Address:</b>	NO. 5, LI-HSIN RD.III, HSINCHU SCIENCE PARK
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<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17010890
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	67407-842
<b>NAME OF SUBMITTER:</b>	JUSTIN KING
<b>SIGNATURE:</b>	/Justin King/
<b>DATE SIGNED:</b>	09/03/2020

	This document serves as an Oath/Declaration (37 CFR 1.63).
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**Total Attachments: 4**

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Serial No. \_\_\_\_\_  
Attorney Docket No. \_\_\_\_\_  
Ref. No. P201909003-US  
Sundial Ref. No. US14647PAMY

## Combined Declaration and Assignment for Patent Application

In Chinese/English

### 美國專利申請聲明以及美國專利轉讓

For the subject matter which is claimed and for which a patent is sought on the invention entitled:  
專利申請權利要求的發明名稱如下:

#### COMPARING CIRCUIT AND COMPARING MODULE WITH HYSTERESIS

I hereby declare that: As a below named inventor  
我在此宣告: 作為下述發明者

The specification of which is attached hereto unless the following box is checked 並將其說明書在此附上, 除非以下  
方格已打叉:

☐ was filed on 其發明已立案于

as United States Application Number or PCT International Application Number 其美國申請號碼或PCT國際申請號碼為

The above-identified application was made or authorized to be made by me.  
以上所提之申請案係由我撰寫或是在我的授權下所撰寫。

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.  
我相信我是首創發明者或是首創共同發明者。

I hereby acknowledge that willful false statements made in this statement is punishable under 18 U.S.C. 1001 by fine  
or/and imprisonment of not more than five (5) years.  
我了解, 按照美國法規第十八節第一千零一項, 任何蓄意偽造的聲明都可受到罰款和/或五年以下有期徒刑。

## ASSIGNMENT

### 美國專利轉讓

WHEREAS, I(we), the named inventor(s), whose post office address(es) appear(s) below, hereinafter referred to as  
ASSIGNOR.  
作為下述其郵遞地址的發明者, 在此稱轉讓人。

WHEREAS, Faraday Technology Corporation whose post office address is C302, No.1355 JinJiHu Avenue  
International Science&Technology Park, Suzhou Industrial Park, P.R.C. and FARADAY TECHNOLOGY  
CORPORATION whose post office address is No.5, Li-Hsin Rd.III, Hsinchu Science Park, Hsinchu, Taiwan 300,  
R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the  
United States and its territorial possessions.

智原微電子(蘇州)有限公司位於中國蘇州工業園區金雞湖大道1355號國際科技園C302與智原科技股份有限公司位於台  
灣300新竹市東區新竹科學工業園區力行三路5號, 在此稱讓受人, 取得此發明在美國與其管轄境內之所有權利。

Serial No. \_\_\_\_\_  
Attorney Docket No. \_\_\_\_\_  
Ref. No. P201909003-US  
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NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part, and reissue of said application for the full term or terms for which the same may be granted, including all priority rights under any International Convention.

根據所收到的相關價值，轉讓人據此將本發明轉讓於讓受人。此轉讓包括本發明以及本發明案之所有在美國的相關權利，包括任何專利有效期間內的分案，續案，重新核發案，並包括在國際公約所保障的優先權。

ASSIGNOR further covenants that no assignments, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

轉讓人將不會簽署任何與此轉讓書相悖的再轉讓，販售，或合同協議。

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE's expense, to identify and communicate to ASSIGNEE at ASSIGNEE's request documents and information concerning the INVENTION that are within ASSIGNOR's possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance, litigation and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR's obligations under this instrument shall extend to ASSIGNOR's heirs, executors, administrators and other legal representatives;

轉讓人將無條件協助簽署任何法律上所需要與本發明相關的文件，包括提交申請，回駁答辯，年費，以及任何證明讓受人擁有本發明之文件。在讓受人的要求下，轉讓人也將無條件協助讓受人，提供讓受人轉讓人所持有的發明文件資料，並提供讓受人或是讓受人的法定繼承人在法律上所要求的回駁答辯，侵權訴訟相關協助。

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE's sole use and behoof; and for the use and behoof of ASSIGNEE's legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

轉讓人在此要求美國專利商標局在核發本發明專利時，跟據以上所呈請讓受人在本發明以及本發明案之所有在美國的相關權利，核發於讓受人。

Legal Name of the Sole Or First Inventor 第一或是為一發明者正式名字			
First And Middle Name 發明者名 <b>Xiao-Dong</b>		Last Name of Inventor 發明者姓 <b>FEI</b>	
Signature 發明者簽字 <i>Xiao-Dong Fei</i>		Signature Date (month/day/year) 簽字日期(月/日/年) <i>9/1/2020</i>	
Residence: City 居住之縣市 <b>Hsinchu</b>	State 省	Citizenship 國籍 <b>People's Republic of China</b>	
Mailing Address 郵寄地址 <b>No.5, Li-Hsin Rd.III, Hsinchu Science Park, Hsinchu, Taiwan 300, R.O.C.</b>			
City 縣市 <b>Hsinchu</b>	State 省	Zip 郵遞區號 <b>300</b>	Country 國家 <b>Taiwan, R.O.C.</b>

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Legal Name of the Joint Inventor 共同發明者正式名字			
First And Middle Name 發明者名 <b>Wei</b>		Last Name of Inventor 發明者姓 <b>WANG</b>	
Signature 發明者簽字 <i>Wei Wang</i>		Signature Date (month/day/year) 簽字日期(月/日/年) <i>9/1/2020</i>	
Residence: City 居住之縣市 <b>Hsinchu</b>	State 省	Citizenship 國籍 <b>People's Republic of China</b>	
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Legal Name of the Joint Inventor 共同發明者正式名字			
First And Middle Name 發明者名 <b>San-Yueh</b>		Last Name of Inventor 發明者姓 <b>HUANG</b>	
Signature 發明者簽字		Signature Date (month/day/year) 簽字日期(月/日/年)	
Residence: City 居住之縣市 <b>Hsinchu</b>	State 省	Citizenship 國籍 <b>Taiwan, R.O.C.</b>	
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Legal Name of the Joint Inventor 共同發明者正式名字			
First And Middle Name 發明者名 <b>Wei</b>		Last Name of Inventor 發明者姓 <b>WANG</b>	
Signature 發明者簽字		Signature Date (month/day/year) 簽字日期(月/日/年)	
Residence: City 居住之縣市 <b>Hsinchu</b>	State 省	Citizenship 國籍 <b>People's Republic of China</b>	
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Legal Name of the Joint Inventor 共同發明者正式名字			
First And Middle Name 發明者名 <b>San-Yueh</b>		Last Name of Inventor 發明者姓 <b>HUANG</b>	
Signature 發明者簽字 		Signature Date (month/day/year) 簽字日期(月/日/年) <b>8/14/2020</b>	
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